

A black, rectangular electronic component, likely a power MOSFET, with multiple pins and a label. The component is shown from a perspective view, highlighting its top surface and side pins. A small white label is visible on the bottom right corner of the component.

- a) Adopting new 4th generation planar IGBT chip, which performance is improved by $1\mu\text{m}$ fine rule process.
For example, typical $V_{CE(sat)}=1.7\text{V}$
- b) Using new Diode which is designed to get soft reverse recovery characteristics.
 - 3ϕ 200A, 600V Current-sense IGBT for 15kHz switching
 - Monolithic gate drive & protection logic
 - Detection, protection & status indication circuits for over-current, short-circuit, over-temperature & under-voltage
 - Acoustic noise-less 22kW class inverter application

General purpose inverter, servo drives and other motor controls

Technical drawing of the SDD-B connector, showing dimensions in mm.

Top View Dimensions:

- Overall width: 135 ± 1
- Overall height: 120.5 ± 0.5
- Distance from left edge to center of first pin: 39.7
- Distance from center of first pin to center of last pin: 74.4
- Distance from center of last pin to right edge: 39.7
- Distance from left edge to center of mounting hole: 10.5
- Distance from center of mounting hole to center of last pin: 10.5
- Distance from center of last pin to center of mounting hole: 10.5
- Distance from center of mounting hole to right edge: 10.5
- Distance from left edge to center of mounting hole: 10.5
- Distance from center of mounting hole to center of last pin: 10.5
- Distance from center of last pin to center of mounting hole: 10.5
- Distance from center of mounting hole to right edge: 10.5
- Distance from left edge to center of mounting hole: 10.5
- Distance from center of mounting hole to center of last pin: 10.5
- Distance from center of last pin to center of mounting hole: 10.5
- Distance from center of mounting hole to right edge: 10.5

Side View Dimensions:

- Overall height: 110 ± 1
- Distance from top edge to center of mounting hole: 95.5 ± 0.5
- Distance from center of mounting hole to bottom edge: 14.5
- Distance from top edge to center of mounting hole: 11
- Distance from center of mounting hole to bottom edge: 11

Front View Dimensions:

- Overall width: 135 ± 1
- Overall height: 120.5 ± 0.5
- Distance from left edge to center of first pin: 39.7
- Distance from center of first pin to center of last pin: 74.4
- Distance from center of last pin to right edge: 39.7
- Distance from left edge to center of mounting hole: 10.5
- Distance from center of mounting hole to center of last pin: 10.5
- Distance from center of last pin to center of mounting hole: 10.5
- Distance from center of mounting hole to right edge: 10.5
- Distance from left edge to center of mounting hole: 10.5
- Distance from center of mounting hole to center of last pin: 10.5
- Distance from center of last pin to center of mounting hole: 10.5
- Distance from center of mounting hole to right edge: 10.5

Other Dimensions:

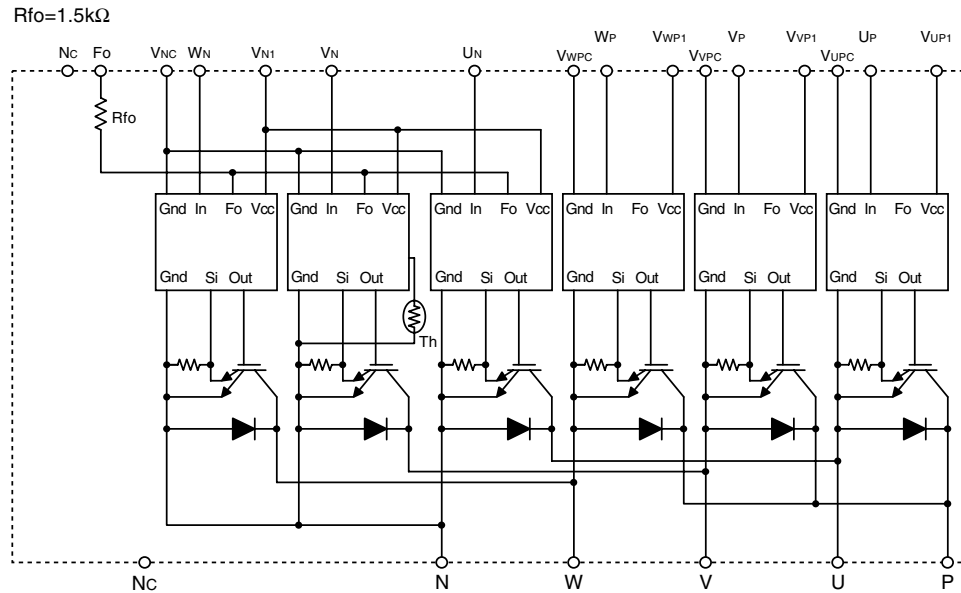
- Distance from left edge to center of mounting hole: 10.5
- Distance from center of mounting hole to center of last pin: 10.5
- Distance from center of last pin to center of mounting hole: 10.5
- Distance from center of mounting hole to right edge: 10.5
- Distance from left edge to center of mounting hole: 10.5
- Distance from center of mounting hole to center of last pin: 10.5
- Distance from center of last pin to center of mounting hole: 10.5
- Distance from center of mounting hole to right edge: 10.5

1. V_{UPC}
2. U_P
3. V_{UP1}
4. V_{VPC}
5. V_P
6. V_{VP1}
7. V_{WPC}
8. W_P
9. V_{WP1}
10. V_{NC}
11. V_{N1}
12. N_C
13. U_N
14. V_N
15. W_N
16. F_O

A : DETAIL

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FLAT-BASE TYPE
INSULATED PACKAGE

INTERNAL FUNCTIONS BLOCK DIAGRAM**MAXIMUM RATINGS** ($T_j = 25^\circ\text{C}$, unless otherwise noted)**INVERTER PART**

Symbol	Parameter	Condition	Ratings	Unit
V_{CES}	Collector-Emitter Voltage	$V_D = 15\text{V}$, $V_{CIN} = 15\text{V}$	600	V
$\pm I_C$	Collector Current	$T_C = 25^\circ\text{C}$	200	A
$\pm I_{CP}$	Collector Current (Peak)	$T_C = 25^\circ\text{C}$	400	A
P_C	Collector Dissipation	$T_C = 25^\circ\text{C}$	595	W
T_j	Junction Temperature		$-20 \sim +150$	$^\circ\text{C}$

CONTROL PART

Symbol	Parameter	Condition	Ratings	Unit
V_D	Supply Voltage	Applied between : $V_{UP1}-V_{UPC}$ $V_{VP1}-V_{VPC}$, $V_{WP1}-V_{WPC}$, $V_{N1}-V_{NC}$	20	V
V_{CIN}	Input Voltage	Applied between : U_P-V_{UPC} , V_P-V_{VPC} W_P-V_{WPC} , $U_N \cdot V_N \cdot W_N-V_{NC}$	20	V
V_{FO}	Fault Output Supply Voltage	Applied between : $FO-V_{NC}$	20	V
I_{FO}	Fault Output Current	Sink current at FO terminal	20	mA

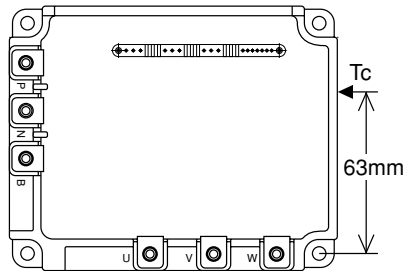
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TOTAL SYSTEM

Symbol	Parameter	Condition	Ratings	Unit
V _{CC(prot)}	Supply Voltage Protected by OC & SC	V _D = 13.5 ~ 16.5V, Inverter Part, T _j = 125°C Start	400	V
V _{CC(surge)}	Supply Voltage (Surge)	Applied between : P-N, Surge value or without switching	500	V
T _c	Module Case Operating Temperature	(Note-1)	-20 ~ +100	°C
T _{stg}	Storage Temperature		-40 ~ +125	°C
V _{iso}	Isolation Voltage	60Hz, Sinusoidal, Charged part to Base, AC 1 min.	2500	V _{rms}

(Note-1) T_c measurement point is as shown below. (Base plate depth 3mm)



THERMAL RESISTANCES

Symbol	Parameter	Test Condition	Limits			Unit
			Min.	Typ.	Max.	
R _{th(j-c)Q}	Junction to case Thermal Resistances	Inverter IGBT part (per 1 element), (Note-1)	—	—	0.21	°C/W
R _{th(j-c)F}		Inverter FWDi part (per 1 element), (Note-1)	—	—	0.35	
R _{th(j-c')Q}		Inverter IGBT part (per 1 element), (Note-2)	—	—	0.13	
R _{th(j-c')F}		Inverter FWDi part (per 1 element), (Note-2)	—	—	0.21	
R _{th(c-f)}	Contact Thermal Resistance	Case to fin, Thermal grease applied (per 1 module)	—	—	0.018	

(Note-2) T_c measurement point is just under the chips.

If you use this value, R_{th(f-a)} should be measured just under the chips.

ELECTRICAL CHARACTERISTICS (T_j = 25°C, unless otherwise noted)

INVERTER PART

Symbol	Parameter	Test Condition		Limits			Unit
				Min.	Typ.	Max.	
V _{CE(sat)}	Collector-Emitter Saturation Voltage	V _D = 15V, I _C = 200A V _{CIN} = 0V, Pulsed (Fig. 1)	T _j = 25°C	—	1.7	2.3	V
			T _j = 125°C	—	1.7	2.3	
V _{EC}	FWDi Forward Voltage	-I _C = 200A, V _D = 15V, V _{CIN} = 15V (Fig. 2)		—	2.2	3.3	V
t _{on}	Switching Time	V _D = 15V, V _{CIN} = 15V↔0V V _{CC} = 300V, I _C = 200A T _j = 125°C Inductive Load (upper and lower arm) (Fig. 3)		0.4	0.8	2.0	μs
t _{rr}				—	0.15	0.3	
t _{c(on)}				—	0.4	1.0	
t _{off}				—	2.0	2.9	
t _{c(off)}				—	0.6	1.2	
I _{CES}	Collector-Emitter Cutoff Current	V _{CE} = V _{CES} , V _{CIN} = 15V (Fig. 4)	T _j = 25°C	—	—	1	mA
			T _j = 125°C	—	—	10	

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CONTROL PART

Symbol	Parameter	Test Condition	Limits			Unit
			Min.	Typ.	Max.	
Id	Circuit Current	V _D = 15V, V _{CIN} = 15V	VN1-VNC	52	72	mA
			VXP1-VXPC	13	18	
V _{th(ON)}	Input ON Threshold Voltage	Applied between : UP-VUPC, VP-VVPC, WP-VWPC UN • VN • WN-VNC	1.2	1.5	1.8	V
V _{th(OFF)}	Input OFF Threshold Voltage		1.7	2.0	2.3	
OC	Over Current Trip Level	V _D = 15V (Fig. 5.6)	T _j = -20°C	—	1010	A
			T _j = 25°C	518	609	
			T _j = 125°C	310	—	
SC	Short Circuit Trip Level	-20 ≤ T _j ≤ 125°C, V _D = 15V (Fig. 5.6)	—	560	—	A
t _{off(OC)}	Over Current Delay Time	V _D = 15V (Fig. 5.6)	—	10	—	μs
OT	Over Temperature Protection	Base-plate Temperature detection, V _D = 15V	Trip level	111	118	°C
			Reset level	—	100	
UV	Supply Circuit Under-Voltage Protection	-20 ≤ T _j ≤ 125°C	Trip level	11.5	12.0	V
			Reset level	—	12.5	
I _{FO(H)}	Fault Output Current	V _D = 15V, V _{FO} = 15V (Note-3)	—	—	0.01	mA
I _{FO(L)}			—	10	15	
t _{FO}	Minimum Fault Output Pulse Width	V _D = 15V (Note-3)	1.0	1.8	—	ms

(Note-3) Fault output is given only when the internal OC, SC, OT & UV protection.

Fault output of OT protection operate by lower arm.

Fault output of OC, SC protection given pulse.

Fault output of OT, UV protection given pulse while over level.

MECHANICAL RATINGS AND CHARACTERISTICS

Symbol	Parameter	Test Condition	Limits			Unit
			Min.	Typ.	Max.	
—	Mounting torque	Main terminal screw : M5	2.5	3.0	3.5	N • m
—	Mounting torque	Mounting part screw : M5	2.5	3.0	3.5	N • m
—	Weight	—	—	920	—	g

RECOMMENDED CONDITIONS FOR USE

Symbol	Parameter	Test Condition	Recommended value	Unit
V _{CC}	Supply Voltage	Applied across P-N terminals	≤ 400	V
V _D	Control Supply Voltage	Applied between : VUP1-VUPC, VVP1-VVPC VWP1-VWPC, VN1-VNC (Note-4)	15 ± 1.5	V
V _{CIN(ON)}	Input ON Voltage	Applied between : UP-VUPC, VP-VVPC, WP-VWPC UN • VN • WN-VNC	≤ 0.8	V
V _{CIN(OFF)}	Input OFF Voltage		≥ 4.0	
f _{PWM}	PWM Input Frequency	Using Application Circuit input signal of IPM, 3φ sinusoidal PWM VVVF inverter (Fig. 8)	≤ 20	kHz
t _{dead}	Arm Shoot-through Blocking Time	For IPM's each input signals (Fig. 7)	≥ 2.5	μs

(Note-4) Allowable Ripple rating of Control Voltage : dv/dt ≤ ±5V/μs, 2V_{p-p}

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PRECAUTIONS FOR TESTING

- Before applying any control supply voltage (V_D), the input terminals should be pulled up by resistors, etc. to their corresponding supply voltage and each input signal should be kept off state.
After this, the specified ON and OFF level setting for each input signal should be done.
- When performing "OC" and "SC" tests, the turn-off surge voltage spike at the corresponding protection operation should not be allowed to rise above V_{CES} rating of the device.
(These test should not be done by using a curve tracer or its equivalent.)

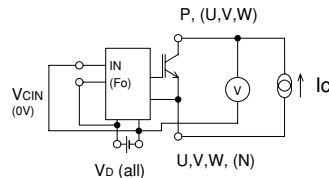


Fig. 1 $V_{CE(sat)}$ Test

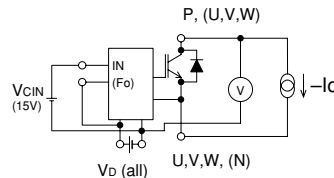
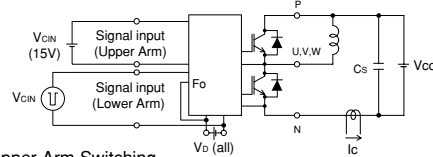


Fig. 2 V_{EC} Test

a) Lower Arm Switching



b) Upper Arm Switching

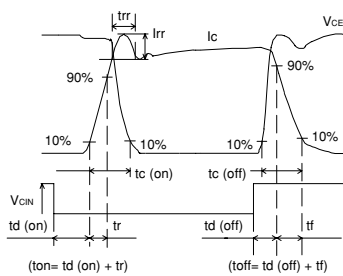
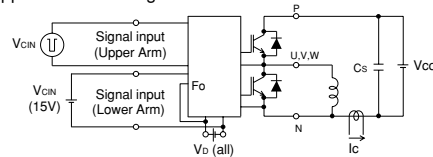


Fig. 3 Switching time Test circuit and waveform

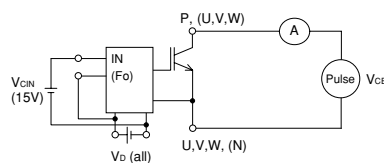


Fig. 4 I_{CES} Test

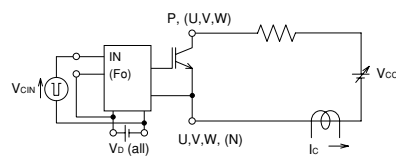


Fig. 5 OC and SC Test

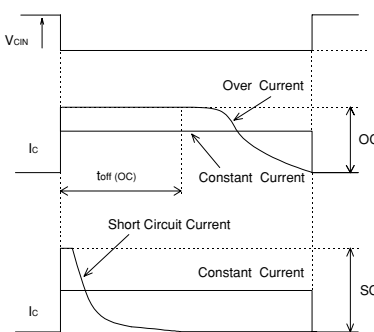


Fig. 6 OC and SC Test waveform

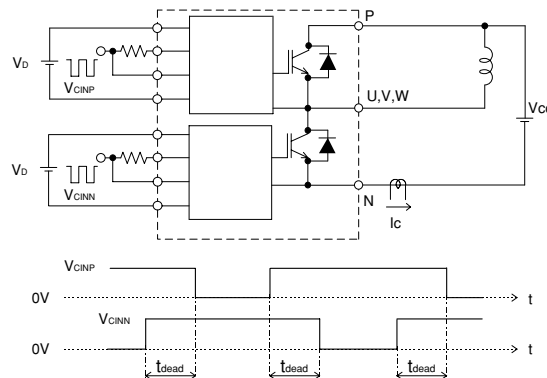


Fig. 7 Dead time measurement point example

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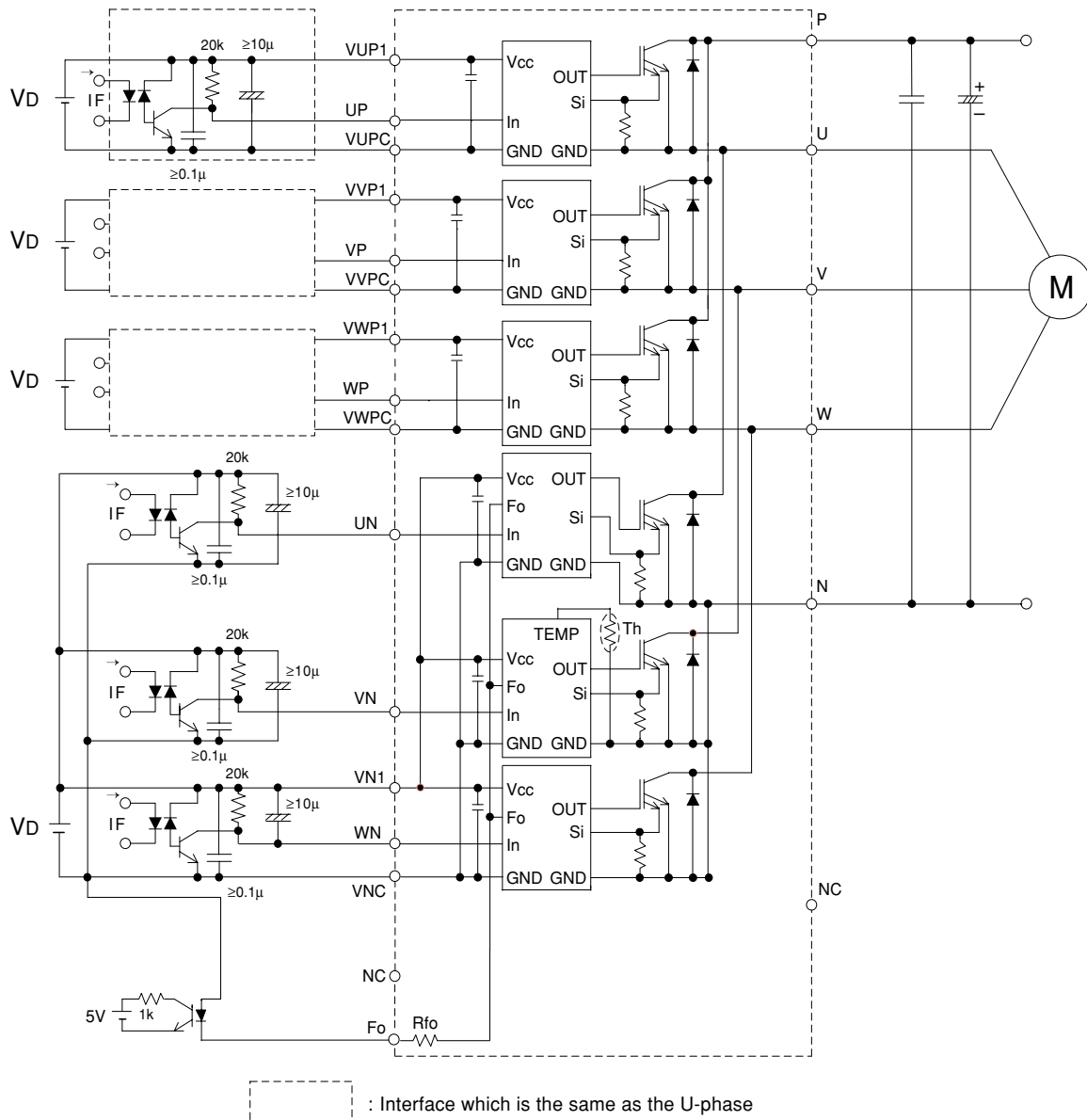


Fig. 8 Application Example Circuit

NOTES FOR STABLE AND SAFE OPERATION ;

- Design the PCB pattern to minimize wiring length between opto-coupler and IPM's input terminal, and also to minimize the stray capacity between the input and output wirings of opto-coupler.
- Quick opto-couplers: $T_{PLH}, T_{PLH} \leq 0.8\mu s$. Use High CMR type. The line between opto-coupler and intelligent module should be shortened as much as possible to minimize the floating capacitance.
- Slow switching opto-coupler: recommend to use at $CTR = 100 \sim 200\%$, Input current = 8 ~ 10mA, to work in active.
- Use 4 isolated control power supplies (VD). Also, care should be taken to minimize the instantaneous voltage charge of the power supply.
- Make inductance of DC bus line as small as possible, and minimize surge voltage using snubber capacitor between P and N terminal.
- Use line noise filter capacitor (ex. 4.7nF) between each input AC line and ground to reject common-mode noise from AC line and improve noise immunity of the system.